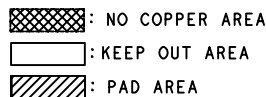
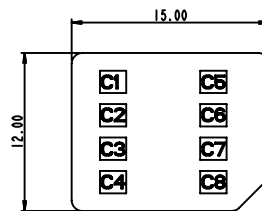


C1	---->	VCC
C2	---->	RST
C3	---->	CLK
C4	---->	RFU
C5	---->	GND
C6	---->	VPP
C7	---->	I/O
C8	---->	RFU



RECOMMENDED PCB LAYOUT  
GENERAL TOLERANCE±0.05  
KEEP ALL OFF THE COMPONENT PROJECT AREA

- Notes:
- Material:  
Plastic Housing: LCP, UL94V-0, Black  
Contact Terminal: Phosphor Bronze  
Cover: SUS301, Thickness=0.15mm
  - Plating:  
Contact Terminal:  
Contact Area: Au 1U<sup>2</sup> Min.  
Solder area: Au 1U<sup>2</sup> Min.  
Underplating: Ni overall 50U<sup>2</sup> Min.  
Cover:  
Underplating: Ni overall 50U<sup>2</sup>  
Solder area: Au 1U<sup>2</sup> Min.
  - Mechanical:  
Life cycles: 5000.
  - Electrical:  
Voltage Rating: 30V AC RMS  
Current Rating: 0.5A AC RMS Max  
Operating Temperature: -20°C to +85°C  
Dielectric Withstanding Voltage: 500V AC (60Sec Min)  
Insulation Resistance: 100MΩ Min  
Contact Resistance: 100mΩ Max
  - RECOMMENDING A METAL MORE THAN 0.15mm THICK.  
PLEASE CONFIRM SOLDERABILITY, IF USE A METAL MASK  
LESS THAN 0.15mm THICK



深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X: ±2' X.X' ±0.5'	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: MICRO SIM 1.8H卡托式
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. : HVC314-SIM08-180
UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	MOLD NO. : /
			DRAW NO. : HVC-2206021059
			SHEET NO. : 1 OF 1